GOMACTech 2027

"Arsenal of Innovation"

Pasadena, CA

March 22 – 25, 2027

www.gomactech.net

Call for Papers

Established in 1968, GOMACTech is the premier forum for reviewing and reporting on developments in microcircuit technologies and applications for government systems as well as announcements and updates of major government microelectronics and semiconductor initiatives.

GOMACTech is an unclassified, export-controlled event. All registrants **must provide proof** of U.S. citizenship or permanent residence status and sign a non-disclosure agreement prior to being permitted entry into the conference.

GOMACTech 2027 features plenary sessions addressing the theme of the **Arsenal of Innovation: Forging American Technological Dominance**, as well as a technical program describing the latest technological advances, including AI and ML in microelectronics, electronics materials, nanoscale devices, quantum information and sensing technologies, photonics, electro-optics, 3D integration, packaging and thermal solutions, rad-hard technology, advances in wide and ultrawide bandgap materials and devices, pulsed power electronics, RF devices and technologies, and trusted, assured, and cyber-secure technologies.

Abstracts are being accepted in the technical topic areas listed below. Authors whose abstracts are accepted—for oral and poster presentations—must submit a complete paper. To ensure correct export control (CUI) markings, authors are required to use the GOMACTech templates. For detailed topic descriptions and to access the mandatory templates, please visit the Paper Submission section of the GOMACTech website.

We are looking forward to your contributions!

SUBMIT ABSTRACTS HERE

Technical Topic Areas

- Advanced Materials and Processes
- Emerging Technologies
- AI and ML in Microelectronics
- High Performance Digital and Mixed-signal Technologies
- Packaging, Integration, Thermal and Control Technologies
- Photonic Technologies, Components, and Systems
- Power Electronics and Emerging Power Technologies
- Radiation Hardened Technologies, Designs, and Systems
- RF Technologies, Components, and Systems
- Trusted, Assured and Cyber-secure Microelectronics

2-page Abstract Due	**Friday, September 11, 2026**
Author Notification	**Friday, November 13, 2026**
Final Full Paper Due	**Friday, January 22, 2027**

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